

NOTES:

1. VIEW FROM C.S.
2. TYPE OF BOARD: 12 LAYERS P.T.H. ORDER OF LAYERS PER LAYER SPECIFICATION.
3. P.C.B. MATERIAL: PER MIL-P-13949F OR IPC-4101.
  - A. BASE MATERIAL: FR-4.
  - B. NOMINAL THICKNESS: 1.7 MM TOLERANCE: CLASS2 (TOLERANCE +/-10%)
  - C. FINAL COPPER FOIL THICKNESS: SEE LAYER SPECIFICATION IN THIS DRAWING.
4. SOLDER MASK: WET FILM DIS M. PER IPC-840 CLASS 2 TYPE B, COLOR BLACK.
5. SILKSCREEN SHALL BE APPLIED TO C.S/P.S ARTWORK, COLOR WHITE.
6. BOARD MARKING TO BE ADDED DATE CODE AND UL94 ONLY.
7. HOLES ARE SPECIFIED AFTER PLATING, HOLE TOLERANCE +0.003" / 0.002".
7. BOARD FINISH PLATING: IMMERTION GOLD.
8. CHECK THE GERBER FILES ACCORDING TO THE NETLIST FILE ATTACHED IN IPC-356 FORMAT BEFORE MANUFACTURING.
9. CONTROL IMPEDANCE IS:
  - A. LAYER 1,12 50 OHM +/-10% FOR 6.0 MILS LINE WIDTH.(REF PLANE L2,L11)
  - B. LAYER 1,12 90 OHM +/-10% DIFFERENTIAL 6 MIL/ 8.5 MIL SPACE/ 6 MIL LINE WIDTH.(REF PLANE L2,L11).
  - C. LAYER 1,12 100 OHM +/-10% DIFFERENTIAL 5 MIL/ 10 MIL SPACE/ 5 MIL LINE WIDTH.(REF PLANE L2,L11).
  - D. LAYER 3,10 50 OHM +/-10% FOR 4.5 MILS LINE WIDTH.(REF PLANE L2,L4 AND L9,L11).
  - E. LAYER 3,10 90 OHM +/-10% DIFFERENTIAL 4.5 MIL/ 5 MIL SPACE/ 4.5 MIL LINE WIDTH.(REF PLANE L2,L4 AND L9,L11).
  - F. LAYER 3,10 100 OHM +/-10% DIFFERENTIAL 4 MIL/ 7 MIL SPACE/ 4 MIL LINE WIDTH.(REF PLANE L2,L4 AND L9,L11).
  - G. LAYER 5,8 50 OHM +/-10% FOR 4.5 MILS LINE WIDTH.(REF PLANE L4,L6 AND L7,L9).

10. DO NOT REMOVE UNUSING PADS ON THE INNER LAYERS.

LAYER STACK-UP		
		TOP S.S
		TOP S.M
before plating-0.5 Oz		SIG-1
1.0 Oz	4.0 MIL	GND-2
0.5 Oz	5.0 MIL	SIG-3
1.0 Oz	5.0 MIL	GND-4
0.5 Oz	5.0 MIL	SIG-5
1.0 Oz	5.0 MIL	GND-6
1.0 Oz	3.0 MIL	VCC-7
0.5 Oz	5.0 MIL	SIG-8
1.0 Oz	5.0 MIL	GND-9
0.5 Oz	5.0 MIL	SIG-10
1.0 Oz	5.0 MIL	GND-11
before plating-0.5 Oz	4.0 MIL	SIG-12
		BOT S.M
		BOT S.S

4

3

2

1